SEMICONDUCTOR

DATA SHEET

YSLCxx01CW Series

LOW CAPACITANCE TVS DIODE ARRAY

APPLICATIONS

- Ethernet 10/100/1000 Base T
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Peripherals
- USB Interface

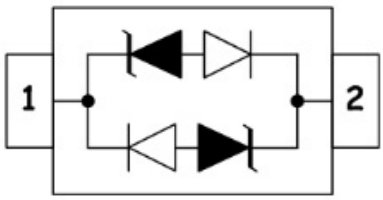
SOD-323



IEC COMPATIBILITY

- IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- IEC61000-4-4 (EFT) 40A (5/50 η s)

PIN CONFIGURATION



FEATURES

- 350 Watts Peak Pulse Power per Line (tp=8/20μs)
- Protects one I/O line (bidirectional)
- Low clamping voltage
- Working voltages: 3.3V, 5V, 8V, 12V, 15V and 24V
- Low leakage current

MECHANICAL CHARACTERISTICS

- JEDEC SOD-323 Package
- Molding Compound Flammability Rating : UL 94V-O
- Weight 5 Millgrams (Approximate)
- Quantity Per Reel : 3,000pcs
- Reel Size : 7 inch
- Lead Finish : Lead Free

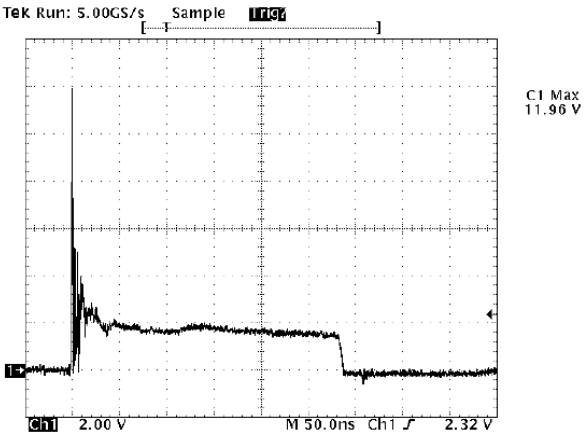
DEVICE CHARACTERISTICS

YSLCxx01CW Series

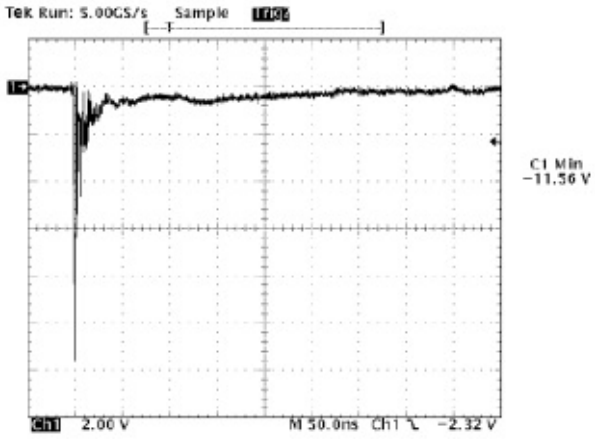
MAXIMUM RATINGS (@ 25℃ Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20μs waveform)	P_{PP}	350	Watts
Lead Soldering Temperature	T_L	260 (10 sec.)	℃
Operating Temperature Range	T_J	-55 ~ 150	℃
Storage Temperature Range	T_{STG}	-55 ~ 150	℃

ELECTRICAL CHARACTERISTICS PER LINE (@ 25℃ Unless Otherwise Specified)								
PART NUMBER	DEVICE MARKING	V_{RWM} (V) (max.)	V_B (V) (min.)	I_T (mA)	V_C (max.)	@A	I_R (μA) (max.)	C_T (pF) (typ.)
YSLC3301CW	L3	3.3	4.0	1	17.8	22	5	3
YSLC0501CW	L5	5.0	6.0	1	22.0	20	5	3
YSLC0801CW	L8	8.0	8.5	1	22.5	12	1	3
YSLC1201CW	LA	12.0	13.3	1	28.3	8	1	3
YSLC1501CW	LB	15.0	16.7	1	32.3	6	1	3
YSLC2401CW	LD	24.0	26.7	1	56.5	5	1	3

ESD Clamping
(8kV Contact per IEC 61000-4-2)

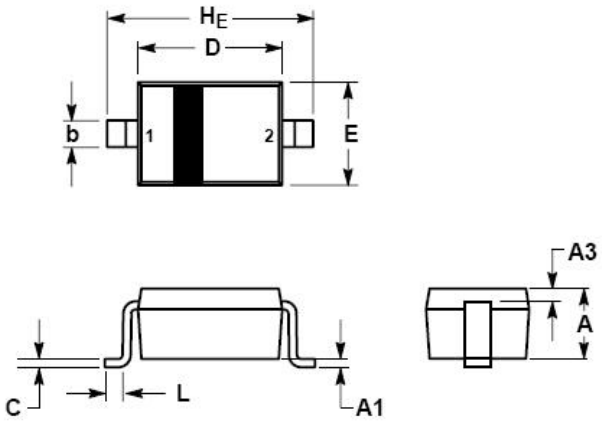


ESD Clamping
(-8kV Contact per IEC 61000-4-2)



PACKAGE OUTLINE & DIMENSIONS

YSLCxx01CW Series



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H_E	2.30	2.50	2.70	0.090	0.098	0.105

* SOLDERING FOOTPRINT

